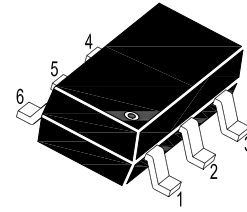
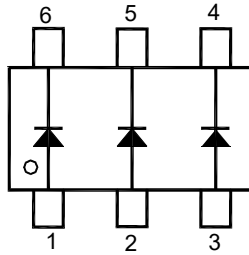


BAS16DW

Silicon Epitaxial Planar Switching Diode

Features

- Fast switching speed
- Ultra-small surface mount package
- For general purpose switching applications
- High conductance



1. Anode 2. Anode 3. Anode
4. Cathode 5. Cathode 6. Cathode
SOT-363 Plastic package

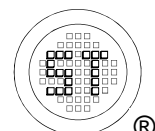
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	75	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Forward Continuous Current	I_{FM}	300	mA
Non-Repetitive Peak Forward Current	I_{FSM}	2 1	A
	$t = 1 \mu\text{s}$ $t = 1 \text{s}$		
Power Dissipation	P_{tot}	200	mW
Operating and Storage Temperature Range	T_j, T_{stg}	- 65 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	625	$^\circ\text{C/W}$

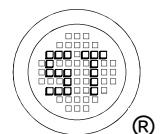
¹⁾ Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



BAS16DW

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 100 \mu\text{A}$	$V_{(BR)R}$	75	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V_F	- - - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}$ at $V_R = 25 \text{ V}, T_j = 150^\circ\text{C}$ at $V_R = 75 \text{ V}, T_j = 150^\circ\text{C}$	I_R	- - - -	25 1 30 50	nA μA μA μA
Total Capacitance at $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	2	pF
Reverse Recovery Time at $I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$	t_{rr}	-	4	ns



Electrical Characteristics Curves

Fig 1. Power Derating Curve

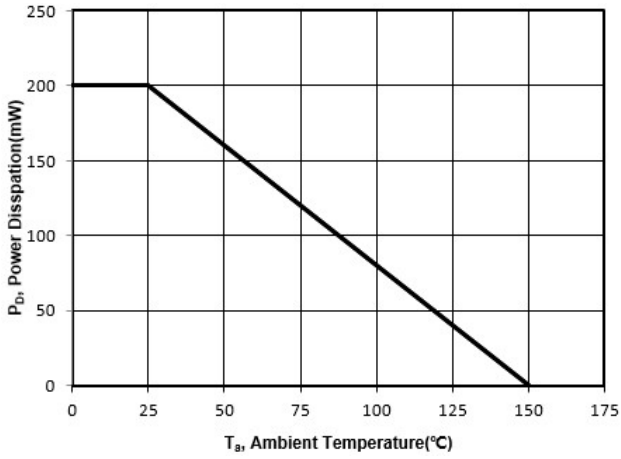


Fig 2. Total Capacitance vs. Reverse Voltage

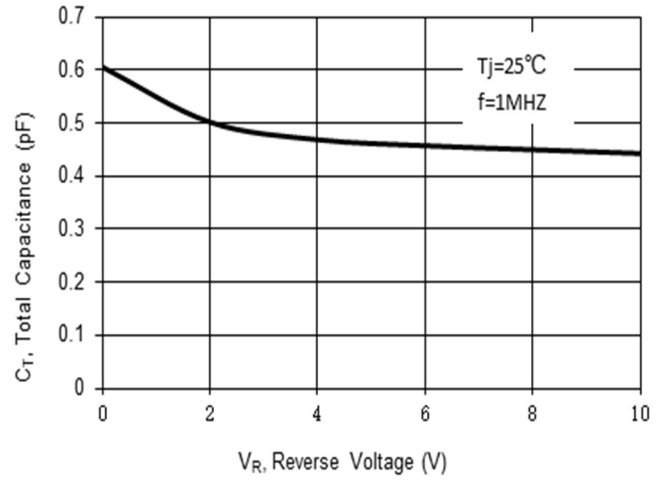


Fig 3. Reverse Current vs. Reverse Voltage

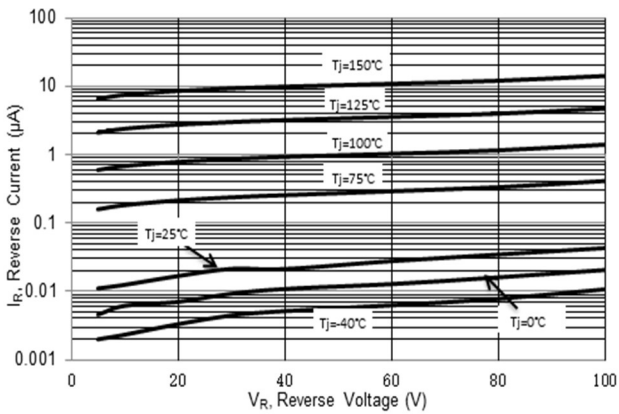
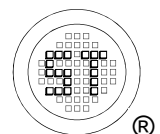
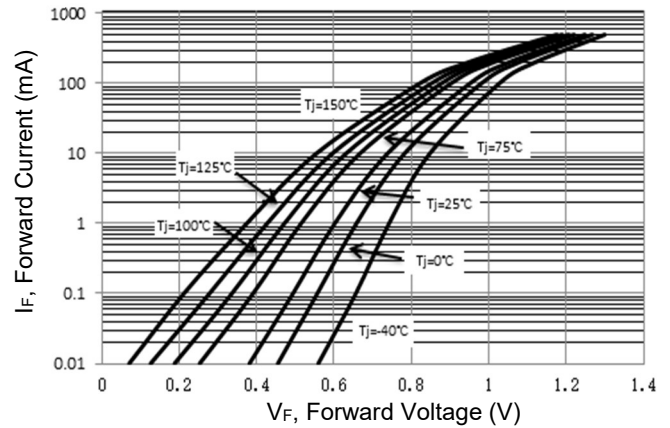


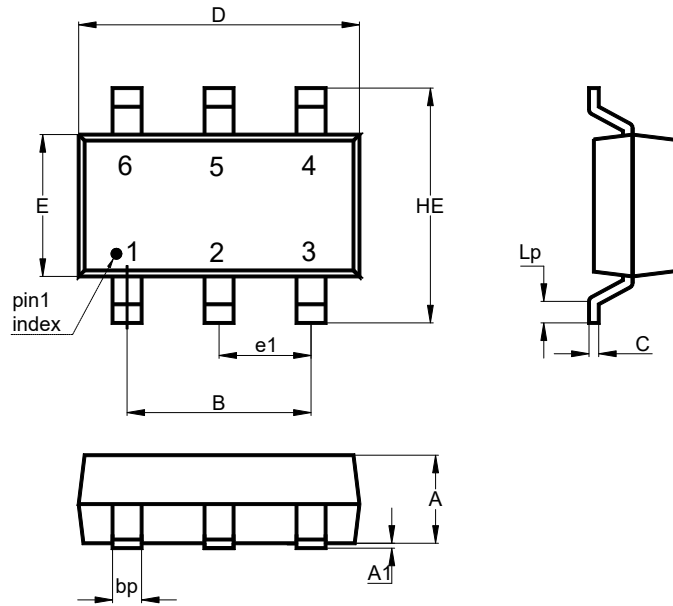
Fig 4. Forward Characteristics



BAS16DW

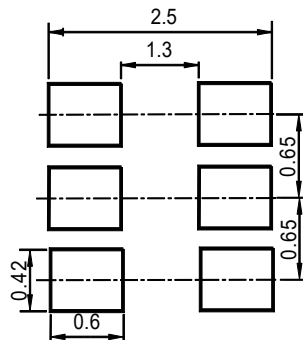
Package Outline (Dimensions in mm)

SOT-363



Unit	A	A1	B	C	D	E	e1	HE	Lp	bp
mm	1.0	0.1	1.3	0.25	2.2	1.35	0.65	2.2	0.4	0.3
	0.9	0	typ.	0.1	1.8	1.15	typ.	2.0	0.15	0.1

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-363	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" KA " = Part No.
 " YM " = Date Code Marking
 " Y " = Year
 " M " = Month
 Font type: Arial

